## Equipment dimensions, weight, and appearance

# Main unit dimensionsDrive partApprox. W300 x D550 x H1090Control panelApprox. W650 x D500 x H400OscillatorApprox. W475 x D500 x H250

Power supply unit

Approx. W465 x D425 x H220

Touch panel

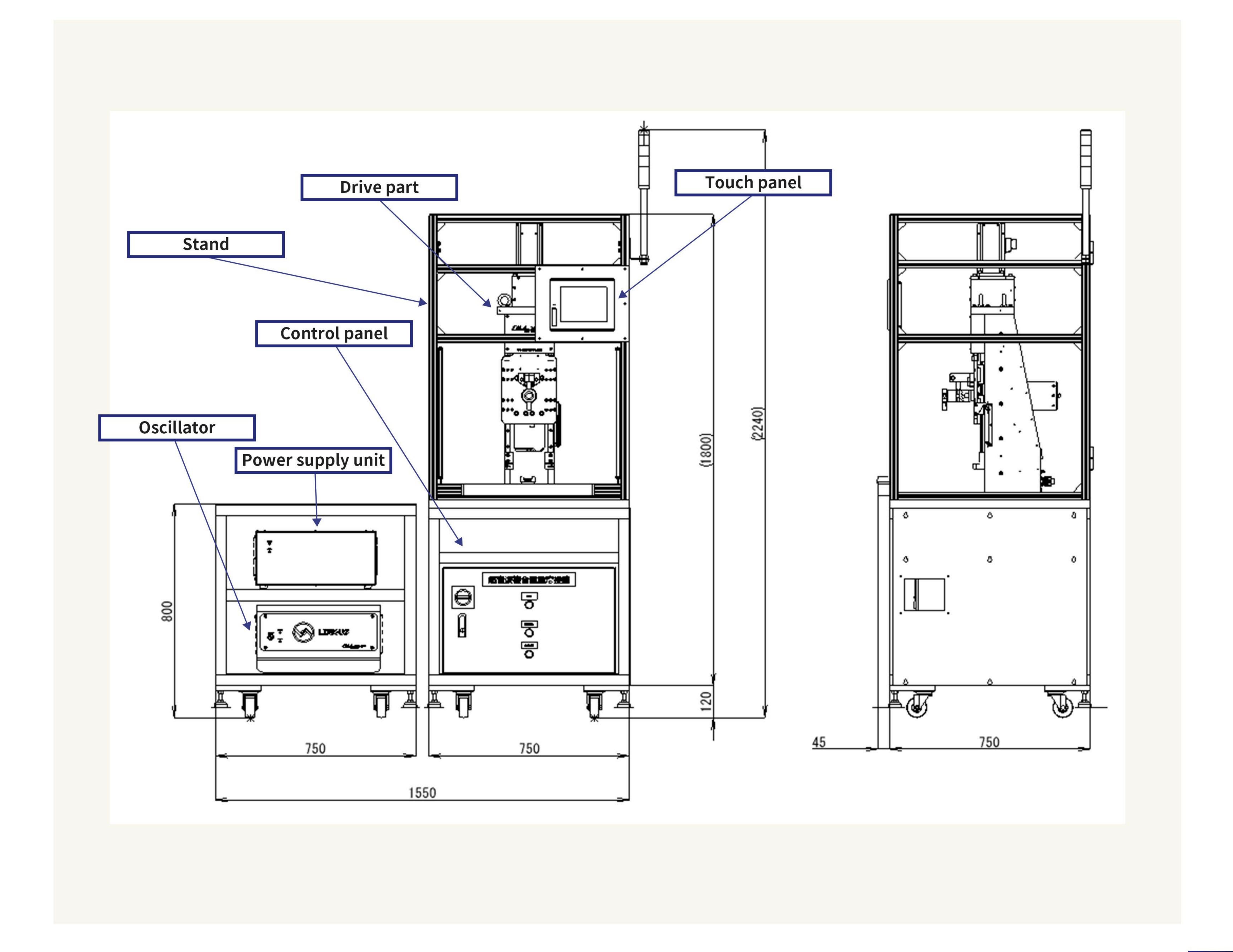
Screen size - 8.4 inches

### Main unit weight

Drive part	Approx. 120 kg
Control panel	Approx. 70 kg
Oscillator	Approx. 30 kg
Power supply unit	Approx. 30 kg
Stand	Approx. 315 kg

## Bonding specifications

Frequency	20 kHz (19 kHz $\pm$ 1 kHz)
Bonding area	Approx. 200 m2 (depending on the workpiece specified by your company)
Drive system	AC servo motor (2 kW)
Control method	Position control, speed control, and push control via AC servo motor (set range: 1 to 4000 N)
Target workpieces	Workpieces designated by your company (next-generation battery parts (all solid state, LIB, etc.), power semiconductor parts, etc.)
Maximum stroke	Distance from horn standby position to maximum bond depth: 90 mm (100 mm for maintenance)



## Power supply, output

Power capacity

Maximum output

Power specifications for overall equipment		
Supply voltage	Three-phase 200 V 50 Hz/60 Hz	
Consumption current	44A	
Power capacity	13kVA	
Power specifications for drive system ————————————————————————————————————		
Supply voltage	Three-phase 200 V 50 Hz/60 Hz	
Consumption current	24A	
Power capacity	7kVA	
Oscillator power specifications ————————————————————————————————————		
Supply voltage	Three-phase 200 V 50 Hz/60 Hz	
Consumption current	20A	

Due to product improvements, specifications and appearance are subject to change without notice. Since products are made to order, the specifications may differ from those listed, depending on the required specifications and options. Thank you for your understanding. Due to product improvements, specifications and appearance are subject to change without notice.

## Configuration and recording

Bonding time	Setting of the bonding time: 0.001 to 9.999 (s)
Pre-burst	Configuration and setting of time to be used as a guide when oscillating while moving down
Pre-shot	Setting of time and static pressure to be used as a guide during preliminary oscillation before bonding
After burst	Configuration and setting of time to be used as a guide for oscillation after bonding
Static pressure	Setting, displaying, and recording of the welding force applied to the bond: 1 to 4000 (N)
Power	Displaying and recording of the power when bonding, and setting of the peak power: 1 to 5000 (W)
Energy	Calculation, recording, and setting of energy when bonding: 0.01 to 99.99 (J)
Bond depth control	<ul> <li>Displaying, recording, and setting of bond sample deformation (Bond dist.): 1 to 5000 (μm)</li> <li>Oscillation stop due to deformation of bond material (Bond dist.): 0.001 to 9.999 (s)</li> </ul>
Variable settings	Variable function (5 levels) for configuration and setting of static pressure to be used as a guide for oscillation during bonding
Process settings	Detailed process entry functions for driving force and oscillation (10 processes)
Threshold settings	Setting of the upper and lower limits for the OK/NG judgment (9 items)
Recipe settings	Registration function for setting bonding conditions, etc. (20 types)
Graph	Process charts (10 processes), oscillation graph (7 types), and trend graph (6 types)
Measurement data output	<ul> <li>SD card output in CSV format (Excel compatible) (15 items)</li> <li>Data transfer via Ethernet or USB2.0 (dedicated software required)</li> <li>Compatible with "GX LogViewer," a Mitsubishi Electric logging data display and analysis tool (free of charge)</li> </ul>
Actual load detection	Piezoelectric force sensor
Conveyance equipment interface	Input/output unit and Ethernet unit are provided

Conveyance equipment interface	Addition of MELSECNET / H unit
Safety mechanism	Area sensor, signal tower, electronic door lock, and magnet catch (with limits)
Position feedback	Displacement meter
Equipment stand	Please refer to the device appearance (touch panel box can also be selected)